

a second supply unit for spraying and supplying a mist comprising additive;  
a third supply unit for spraying and supplying a mist comprising pure water; and  
a mixing unit for mixing the mist of abrasive slurry supplied from said first supply unit, the mist of additive supplied from said second supply unit and the mist of pure water supplied from said third supply unit to form a polishing mixture, said mixing unit supplying the polishing mixture onto said major surface of said polishing table.

2. (Amended) An apparatus including a [A] polishing solution supply system, the polishing solution supply system comprising[,]:

a polishing table for placing a semiconductor substrate on a [the] major surface thereof;

a first supply unit for spraying and supplying a mist comprising abrasive slurry to a specified location on said major surface of said polishing table;

a second supply unit for spraying and supplying a mist comprising additive onto said major surface of said polishing table so as to mix with the mist of abrasive slurry supplied from said first supply unit; and

a third supply unit for spraying and supplying a mist comprising pure water onto said major surface of said polishing table so as to mix with the mist of abrasive slurry supplied from said first supply unit and with the mist of additive supplied from said second supply unit.

3. (Amended) The [polishing solution supply system] apparatus according to claim 1, wherein each of said supply units [having,] comprises:

a tank for storing [each] liquid;

a pipe for supplying said liquid from said tank to said mixing unit;

a pump for supplying said liquid in said tank to said pipe at a [specified] pressure,  
or a gas supply unit for supplying a gas into said tank so as to supply said liquid in said  
tank to said pipe at a [specified] pressure;

a control unit for controlling the pressure of said liquid in said pipe [to a specified  
pressure]; and

a spray unit for spraying said liquid supplied from said pipe into said mixing unit.

4. (Amended) The [polishing solution supply system] apparatus according to  
claim 2, wherein each of said supply units [having,] comprises:

a tank for storing [each] liquid;

a pipe for supplying said liquid in said tank to said pipe at a [specified] pressure,  
or a gas supply unit for supplying a gas into said tank so as to supply said liquid in said  
tank to said pipe at a [specified] pressure;

a control unit for controlling the pressure of said liquid in said pipe [to a specified  
pressure]; and

a spray unit for spraying said liquid supplied from said pipe onto said major  
surface of said polishing table.

5. (Amended) The [polishing solution supply system] apparatus according to  
claim 3, wherein said control unit includes a flow meter for measuring the flow rate of  
liquids in said pipe, said control unit controlling [the] rotating speed of said pump or

controlling the pressure of said gas supplied from said gas supply unit on the basis of the results of measurements by said flow meter.

6. (Amended) The [polishing solution supply system] apparatus according to claim 1, wherein said additive is an aqueous solution of organic acid, or an aqueous solution of hydrogen peroxide.

7. (Amended) The [polishing solution supply system] apparatus according to claim 2, wherein said additive is an aqueous solution of organic acid, or an aqueous solution of hydrogen peroxide.

8. (Amended) [An] The apparatus [for polishing a semiconductor substrate comprising,  
the polishing solution supply system] according to claim 1[; and], comprising  
a carrier head for pressing said semiconductor substrate against said major surface  
of said polishing table.

9. (Amended) [An] The apparatus [for polishing a semiconductor substrate comprising,  
the polishing solution supply system] according to claim 2[; and], comprising  
a carrier head for pressing said semiconductor substrate against said major surface  
of said polishing table.

10. (Amended) A method of supplying a polishing solution in an apparatus including a polishing solution supply system, the polishing solution supply system comprising:

a polishing table for placing a semiconductor substrate on a major surface thereof;  
a first supply unit for spraying and supplying a mist comprising additive; a second supply unit for spraying and supplying a mist comprising additive; a third supply unit for spraying and supplying a mist comprising pure water; and a mixing unit for mixing the mist of abrasive slurry supplied from said first supply unit, the mist of additive supplied from said second supply unit and the mist of pure water supplied from said third supply unit to form a polishing mixture, said mixing unit supplying the polishing mixture onto said major surface of said polishing table [through use of the polishing solution supply system according to claim 1], the method comprising [the steps of]:

spraying and supplying each of said mist comprising abrasive slurry, said mist comprising additive and said mist comprising pure water into said mixing unit, and mixing them in said mixing unit to form a polishing mixture; and

supplying the polishing mixture onto said major surface of said polishing table.

11. (Amended) A method of supplying a polishing solution in an apparatus including a polishing solution supply system, the polishing solution supply system, comprising:

a polishing table for placing a semiconductor substrate on a major surface thereof;  
a first supply unit for spraying and supplying a mist comprising abrasive slurry to a specified location on said major surface of said polishing table;

a second supply unit for spraying and supplying a mist comprising additive onto said major surface of said polishing table so as to mix with the mist of abrasive slurry supplied from said first supply unit; and

a third supply unit for spraying and supplying a mist comprising pure water onto said major surface of said polishing table so as to mix with the mist of abrasive slurry supplied from said first supply unit and with the mist of additive supplied from said second supply unit [through use of the polishing solution supply system according to claim 2], the method comprising [a step of] spraying and supplying each of said mist comprising abrasive slurry, said mist comprising additive and said mist comprising pure water onto said major surface of said polishing table so as to mix with each other.

12. (Amended) The method of supplying a polishing solution according to claim 10, further comprising [the steps of] :

measuring [the] a quantity of each of said abrasive slurry, additive and pure water; and

controlling [the] a supply pressure of each [fluid] of said abrasive slurry, said additive and said pure water to a desired value on the basis of the results of measurement.

13. (Amended) The method of supplying a polishing solution according to claim 10, further comprising [a step of] supplying pure water to said mixing unit, when said abrasive slurry is not supplied to said mixing unit for a specified period of time.

14. (Amended) A method of polishing a semiconductor substrate in an apparatus including a polishing solution supply system, the polishing solution supply system comprising: a polishing table for placing a semiconductor substrate on a major surface thereof; a first supply unit for spraying and supplying a mist comprising slurry; a second supply unit for spraying and supplying a mist comprising additive; a third supply unit for spraying and supplying a mist comprising pure water; and a mixing unit for mixing the mist of abrasive slurry supplied from said first supply unit, the mist of additive supplied from said second supply unit and the mist of pure water supplied from said third supply unit to form a polishing mixture, said mixing unit supplying the polishing mixture onto said major surface of said polishing table; and a carrier head for pressing said semiconductor substrate against said major surface of said polishing table, while pressing the semiconductor substrate against [a] said polishing table using said [a] carrier head, [in the apparatus for polishing a semiconductor substrate according to claim 8,] the method comprising [the steps of,];

spraying and supplying each of said abrasive slurry, said additive, and said pure water into said mixing unit, and mixing them in said mixing unit; and  
supplying the mixture onto said major surface of said polishing table.

15. (Amended) A method of polishing a semiconductor substrate in an apparatus including a polishing solution supply system, the polishing solution supply system comprising: a polishing table for placing a semiconductor substrate on a major surface thereof; a first supply unit for spraying and supplying a mist comprising abrasive slurry to a specified location on said major surface of said polishing table; a second supply unit for

spraying and supplying a mist comprising additive onto said major surface of said polishing table so as to mix with the mist of abrasive slurry supplied from said first supply unit; and a third supply unit for spraying and supplying a mist comprising pure water onto said major surface of said polishing table so as to mix with the mist of abrasive slurry supplied from said first supply unit and with the mist of additive supplied from said second supply unit; and a carrier head for pressing said semiconductor substrate against said major surface of said polishing table, while pressing the semiconductor substrate against [a] said polishing table using said [a] carrier head, [in the an apparatus for polishing a semiconductor substrate [according to claim 9], the method comprising [the steps of,

spraying and supplying each of said abrasive slurry, said additive, and said pure water onto said major surface of said polishing table so as to mix with each other.

16. (Amended) The [A] method [of manufacturing a semiconductor device through use of the polishing solution supply system] according to claim [1] 10, comprising supplying the polishing solution during manufacturing a semiconductor device.

17. (Amended) The [A] method [of manufacturing a semiconductor device through use of the polishing solution supply system] according to claim [2] 11, comprising spraying and supplying said mist comprising abrasive slurry, said mist comprising additive and said mist comprising pure water during manufacturing a semiconductor device.